



## **SPECIFICATION**

• Supplier : Samsung electro-mechanics • Samsung P/N : CL32A476MQJNNNE

• Product : Multi-layer Ceramic Capacitor • Description : CAP, 47 µF, 6.3V, ±20%, X5R, 1210

## A. Samsung Part Number

<u>CL</u> <u>32</u> <u>A</u> <u>476</u> <u>M</u> <u>Q</u> <u>J</u> <u>N</u> <u>N</u> <u>N</u> <u>E</u> ① ② ③ ④ ⑤ ⑥ ⑦ ⑧ ⑨ ⑩ ⑪

① S	Series	Samsung Multi-layer Ceramic Capacitor									
② S	Size	1210 (	inch c	ode)	L: 3.2	± 0.3	mm	W:	2.5	± 0.2	mm
3 D	Dielectric	X5R			8	Inner e	electrode		Ni		
4 C	Capacitance	<b>47</b> μ	ιF			Termin	nation		Cu		
⑤ C	Capacitance	±20 %	%			Plating	J		Sn 10	00%	(Pb Free)
to	olerance				9	Produc	ct		Norm	al	
6 R	Rated Voltage	6.3 √	/		10	Specia	ıl		Rese	rved for	future use
⑦ T	Thickness	2.5 ±	0.2	mm	11	Packag	ging		Embo	ssed T	ype, 7" reel

## B. Samsung Reliablility Test and Judgement condition

	Performance	Test condition						
Capacitance	Within specified tolerance	120Hz ±20% 0.5±0.1Vrms						
Tan δ (DF)	0.1 max.							
Insulation	10,000Mohm or 100Mohm⋅ <i>μ</i> F	Rated Voltage 60~120 sec.						
Resistance	Whichever is Smaller							
Appearance	No abnormal exterior appearance	Microscope (×10)						
Withstanding	No dielectric breakdown or	250% of the rated voltage						
Voltage	mechanical breakdown							
Temperature	X5R							
Characterisitcs	(From -55 $^{\circ}\!$							
Adhesive Strength	No peeling shall be occur on the	500g·F, for 10±1 sec.						
of Termination	terminal electrode							
Bending Strength	Capacitance change: within ±12.5%	Bending to the limit (1mm)						
		with 1.0mm/sec.						
Solderability	More than 75% of terminal surface	SnAg3.0Cu0.5 solder						
	is to be soldered newly	245±5℃, 3±0.3sec.						
		(preheating : 80~120℃ for 10~30sec.)						
Resistance to	Capacitance change: within ±7.5%	Solder pot : 270±5℃, 10±1sec.						
Soldering heat	Tan δ, IR : initial spec.							

	Performance	Test condition
Vibration Test	Capacitance change: within ±5%	Amplitude : 1.5mm
	Tan δ, IR : initial spec.	From 10Hz to 55Hz (return : 1min.)
		2hours × 3 direction (x, y, z)
Moisture	Capacitance change: within ±12.5%	With rated voltage
Resistance	Tan δ : 0.125 max	40±2℃, 90~95%RH, 500+12/-0hrs
	IR: $12.5 \text{M}\Omega \cdot \mu\text{F}$ or Over	
High Temperature	Capacitance change : within ±12.5%	With 150% of the rated voltage
Resistance	Tan δ : 0.125 max	Max. operating temperature
	IR : 25MΩ·μF or Over	
		1000+48/-0hrs
Temperature	Capacitance change: within ±7.5%	1 cycle condition
Cycling	Tan δ, IR : initial spec.	Min. operating temperatur → 25°C
		$ ightarrow$ Max. operating temperature $ ightarrow$ 25 $^{\circ}$ C
		5 cycle test

## C. Recommended Soldering method :

Reflow ( Reflow Peak Temperature : 260+0/-5  $^{\circ}$ C, 10sec. Max )

<sup>\*</sup> For the more detail Specification, Please refer to the Samsung MLCC catalogue.